

## N-Channel 40V(D-S) MOSFET

Product summary		
$V_{DS}$	40	V
$R_{DS(ON)}$ (at $V_{GS}=10V$ ) Typ.	7.6	$m\Omega$
$R_{DS(ON)}$ (at $V_{GS}=4.5V$ ) Typ.	9.9	$m\Omega$
$I_D(T_c=25^\circ C)$	30	A

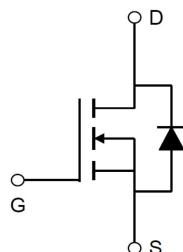
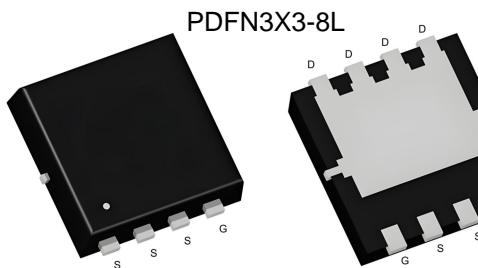
### Features

- Advanced Trench Technology
- Low  $R_{DS(ON)}$

### Applications

- Load switching
- PWM Applications
- Power Management

### Pin Configuration



### Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECAL30N04A	PDFN3X3-8L	13"	5000pcs

### Absolute Maximum Ratings (at $T_A=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_c=25^\circ C$	A
		$T_c=70^\circ C$	A
$I_{DM}$	Pulse Drain Current Tested <sup>A</sup>	115	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>B</sup>	36	mJ
$P_D$	Power Dissipation @ $T_c=25^\circ C$	15	W
$T_J, T_{STG}$	Junction and Storage Temperature Range	-55 to +150	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{\theta JC}$	Thermal Resistance-Junction to case max	8.3	$^\circ C/W$

Electrical Characteristics (at  $T_J = 25^\circ\text{C}$  Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	40	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1.0	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 20\text{V}$	--	--	$\pm 100$	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance <sup>C</sup>	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=30\text{A}$	--	7.6	10	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=20\text{A}$	--	9.9	13.5	$\text{m}\Omega$
$V_{\text{SD}}$	Diode Forward Voltage	$I_{\text{S}}=30\text{A}, V_{\text{GS}}=0\text{V}$	--	--	1.2	V
Dynamic Parameters <sup>D</sup>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=20\text{V}$ $f=1\text{MHz}$	--	1620	--	pF
$C_{\text{oss}}$	Output Capacitance		--	140	--	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	121	--	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=20\text{V}, I_{\text{D}}=15\text{A}$ $V_{\text{GS}}=10\text{V}$	--	5.2	--	nC
$Q_{\text{gs}}$	Gate-Source Charge		--	2.9	--	nC
$Q_{\text{gd}}$	Gate-Drain Charge		--	1.2	--	nC
$t_{\text{D}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=20\text{V}$ $, R_G=6\Omega, R_L=20\Omega,$ $I_{\text{D}}=1\text{A},$ $V_{\text{GS}}=10\text{V}$	--	10	--	ns
$t_r$	Turn-on Rise Time		--	6.7	--	ns
$t_{\text{D}(\text{off})}$	Turn-off Delay Time		--	19	--	ns
$t_f$	Turn-off Fall Time		--	12	--	ns
$t_{\text{rr}}$	Reverse recovery time	$I_F=5\text{A},$ $di/dt=100 \text{ A/uS}$	--	18.7	--	ns
$Q_{\text{rr}}$	Reverse recovery charge		--	4.5	--	nC

A. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

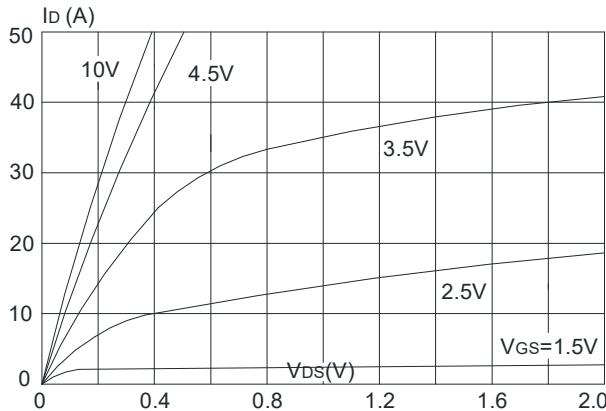
B. EAS condition:  $T_J=25^\circ\text{C}$ ,  $R_G=25\Omega$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $I_{\text{AS}}=12\text{A}$ .

C. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$ .

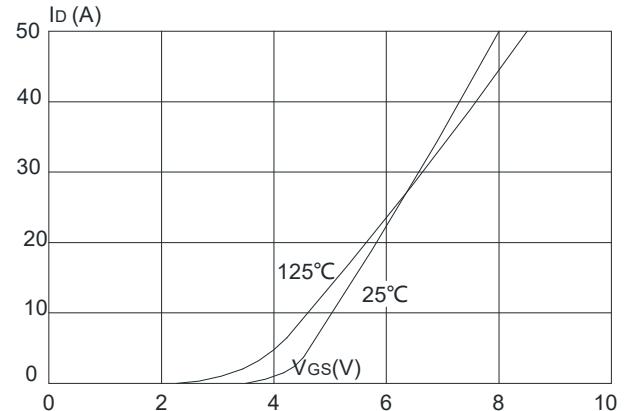
D. Guaranteed by design, not subject to production testing.

## Typical Characteristics

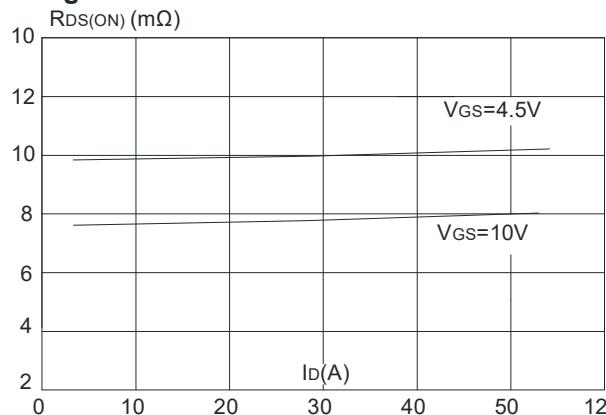
**Figure 1:** Output Characteristics



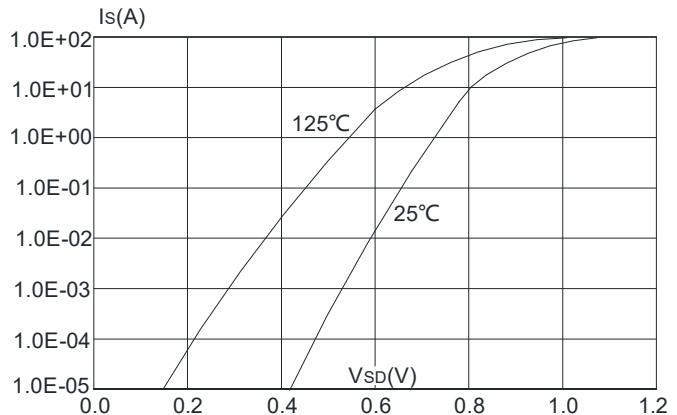
**Figure 2:** Typical Transfer Characteristics



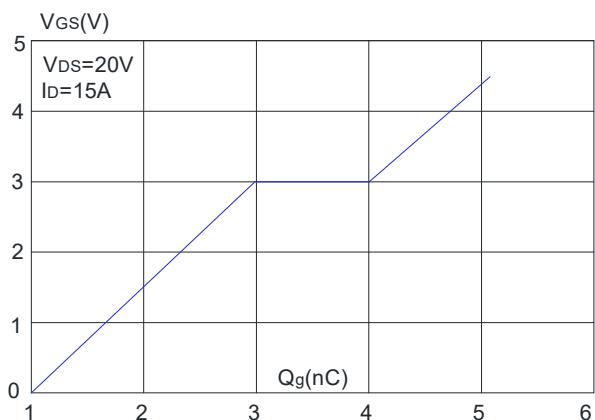
**Figure 3:** On-resistance vs. Drain Current



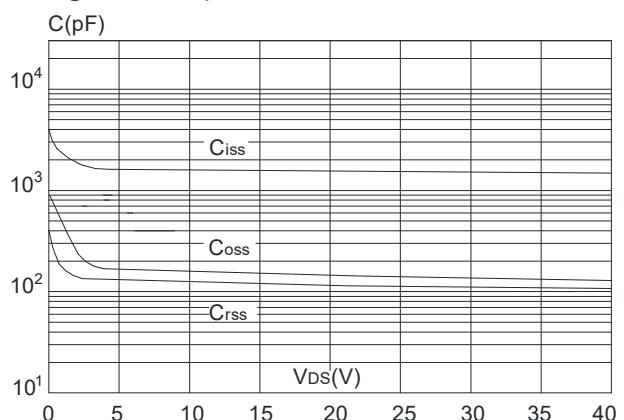
**Figure 4:** Body Diode Characteristics



**Figure 5:** Gate Charge Characteristics

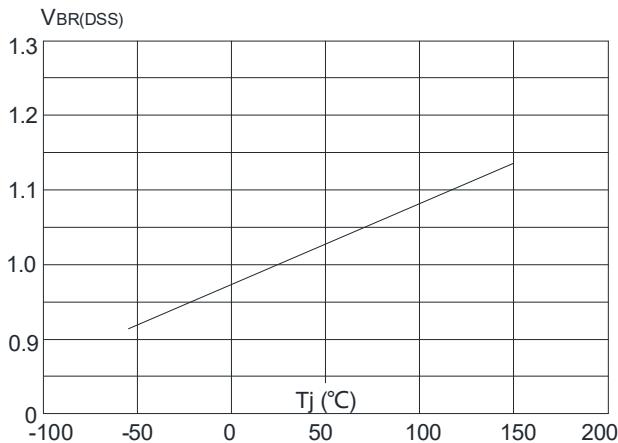


**Figure 6:** Capacitance Characteristics

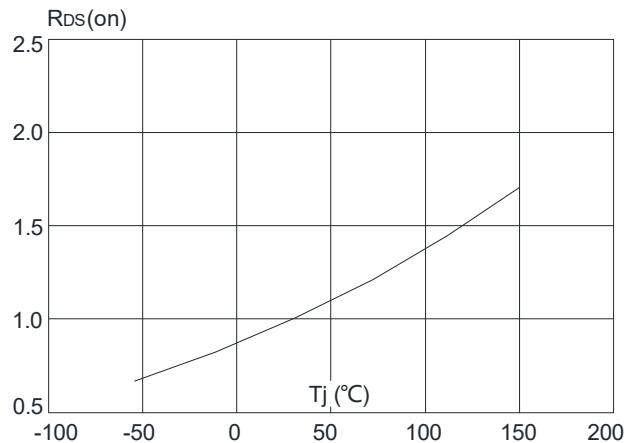


## Typical Characteristics

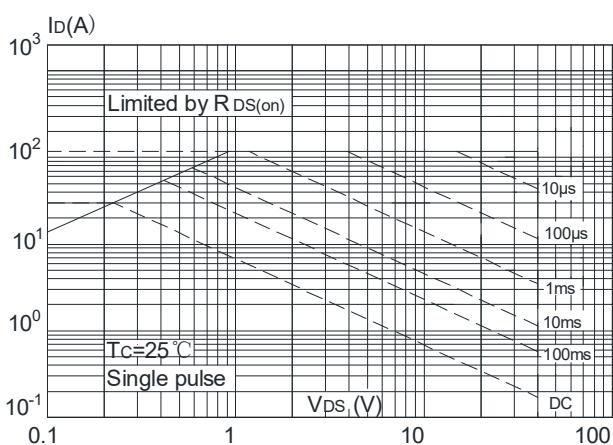
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



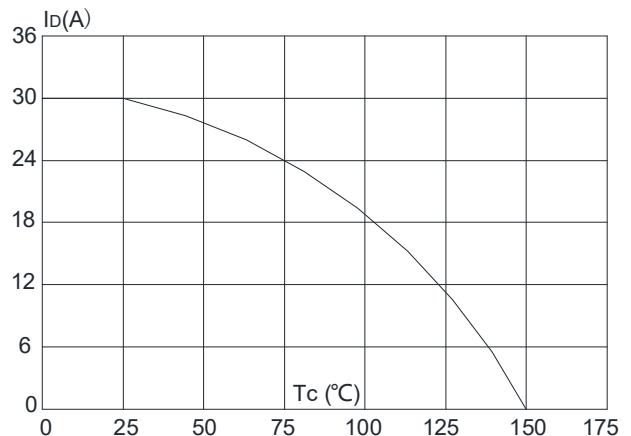
**Figure 8:** Normalized on Resistance vs. Junction Temperature



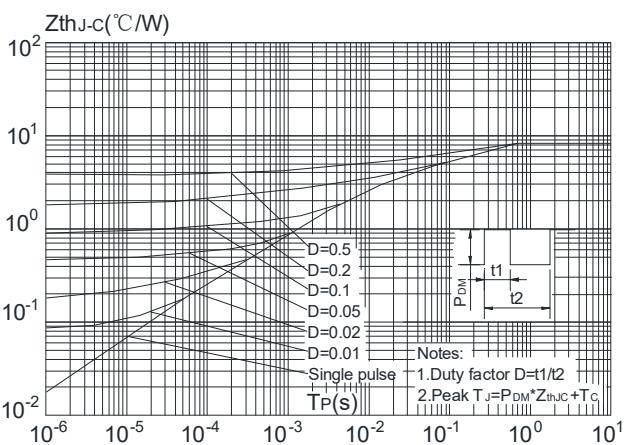
**Figure 9:** Maximum Safe Operating Area

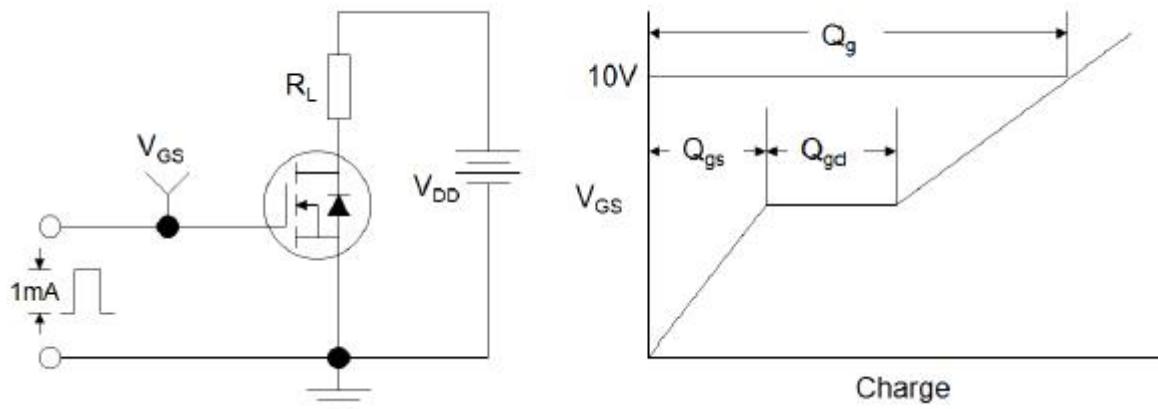
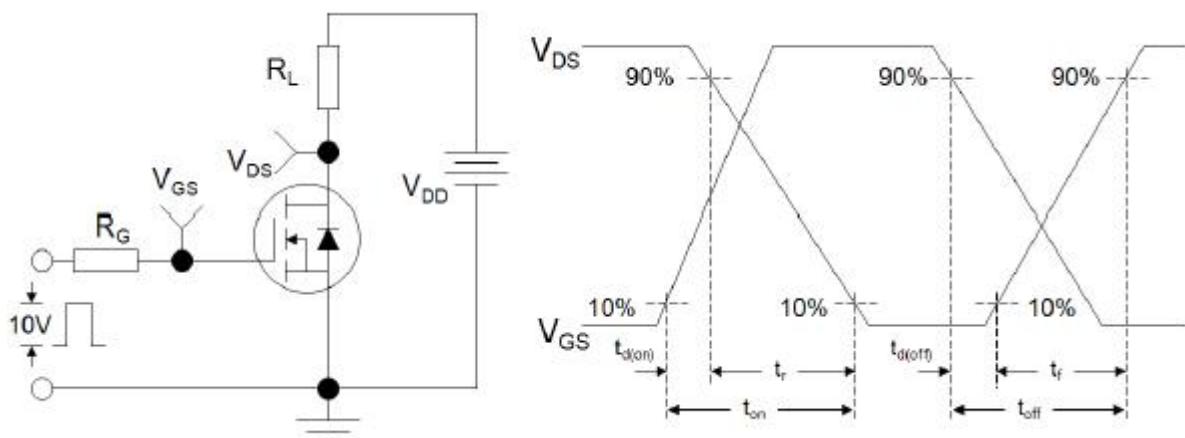
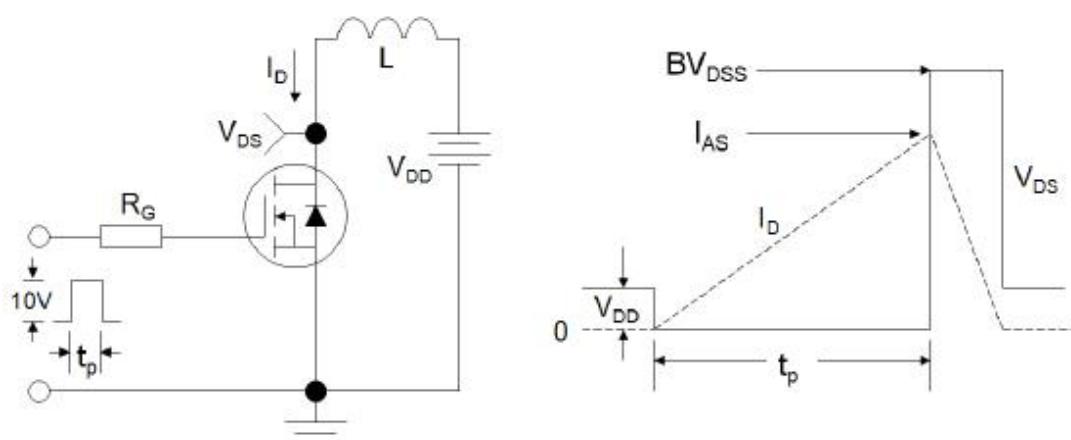


**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature

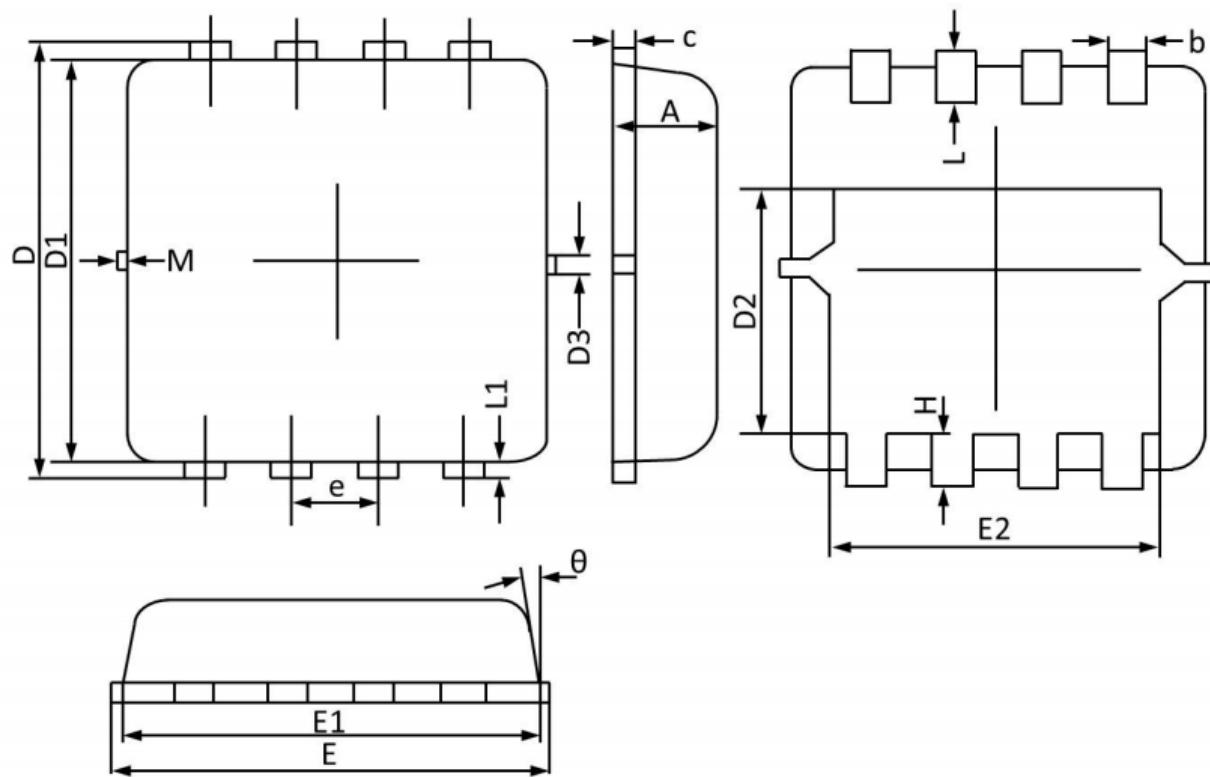


**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



**Test Circuit**

**Figure1:Gate Charge Test Circuit & Waveform**

**Figure 2: Resistive Switching Test Circuit & Waveforms**

**Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms**

## PDFN3X3-8L Package Information (unit:mm)


**DIMENSIONS**

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.70	0.75	0.80	b	0.25	0.30	0.35
C	0.10	0.15	0.25	D	3.25	3.35	3.45
D1	3.00	3.10	3.20	D2	1.78	1.88	1.98
D3	--	0.13	--	E	3.20	3.30	3.40
E1	3.00	3.15	3.20	E2	2.39	2.49	2.59
e	0.65BSC			H	0.30	0.39	0.50
L	0.30	0.40	0.50	L1	--	0.13	--
θ	--	10°	12°	M	*	*	0.15